

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

Do not
enter
HWA
10/4/04

Listing of Claims

1-14. (Cancelled).

15. (Currently amended) A method for producing a flexible thin film capacitor comprising:

forming a metal oxide adhesive film on a substrate formed of at least one selected from the group consisting of an organic polymer and a metal foil, wherein the metal oxide adhesive film comprises at least one metal selected from Cr, NiCr, Ti, Co, Ge, Cu, Sn, Mo and W, and

forming a first metal electrode film, an inorganic high dielectric film and a second metal electrode film in this order on the metal oxide adhesive film, using respective masks;

wherein the first metal electrode film, the inorganic high dielectric film and the second metal dielectric film are formed in contact with the metal oxide adhesive film, thereby being integrated with the substrate by the metal oxide adhesive film,

wherein when the substrate comprises an organic polymer, the method further comprises

forming a peeling film on a base formed of at least one selected from the group consisting of an inorganic material and a metal material, wherein the peeling film is formed of at least one material selected from the group consisting of SiO₂, Si₃N₄ and coating glass;

applying an organic polymer material onto the peeling film; and

curing the organic polymer material by a heat treatment or light irradiation, thereby forming the substrate formed of an organic polymer on the peeling film.